

ABSTRACT OF THE DISCLOSURE

An electronic device module comprises a wiring substrate having an insulating substrate with a porous structure including continuous pores and wiring conductors selectively formed in the porous structure; and an electronic device directly connected to said wiring conductors formed in the porous structure. A manufacturing method of an electronic device module comprises mounting an electronic device on a surface of an insulating substrate having a porous structure including continuous pores and including photosensitive material which produces or vanishes ion exchange groups upon exposure to energy rays using a mask; exposing the energy rays to change the photosensitive material; and performing electroless plating to form wiring conductors in continuous pores generated by the change of the photosensitive material.